



## Reliability Data Report Product Family R413

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LTC987 / LTC1726 / LTC1727 / LTC1728 /  
LTC1921 / LTC1985 / LTC2369 / LTC2900 /  
LTC2901 / LTC2902 / LTC2903 / LTC2904 /  
LTC2906 / LTC2907 / LTC2908 / LTC2909 /  
LTC2910 / LTC2911 / LTC2912 / LTC2913 /  
LTC2914 / LTC2915 / LTC2916 / LTC2917 /  
LTC2918 / LTC2919 / LTC2920 / LTC2923 /  
LTC2924 / LTC2925 / LTC2926 / LTC2927 /  
LTC2928 / LTC2930 / LTC2931 / LTC2932 /  
LTC2951 / LTC2954 / LTC4150 / LTC4257 /  
LTC4261 / LTC4263 / LTC4265 / LTC4267 /  
LTC4301 / LTC4302 / LTC4354

# Reliability Data Report

## Report Number: R413

Report generated on: Wed Jun 18 10:12:09 PDT 2014

<b>OPERATING LIFE TEST</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE HRS (+125°C)<sup>1</sup></b>	<b>No. of FAILURES<sup>2,3</sup></b>
QFN/DFN	619	0421	0839	554	0
SSOP/TSSOP	1127	0213	0721	947	0
SOIC/SOT/MSOP	2099	9914	1251	1782	0
SOT	951	0409	1201	808	0
Totals	4,796	-	-	4,091	0

<b>PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE HRS</b>	<b>No. of FAILURES</b>
QFN/DFN	5630	0325	1321	498	0
SSOP/TSSOP	5547	0436	1322	263	0
SOIC/SOT/MSOP	12655	9924	1314	829	0
SOT	38805	0426	1317	2007	0
Totals	62,637	-	-	3,597	0

<b>TEMP CYCLE FROM -65 TO 150 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE CYCLES</b>	<b>No. of FAILURES</b>
QFN/DFN	5030	0325	1321	1279	0
SSOP/TSSOP	1953	0436	1322	585	0
SOIC/SOT/MSOP	13674	9924	1317	2218	0
SOT	3203	0426	1317	842	0
Totals	23,860	-	-	4,924	0

<b>THERMAL SHOCK FROM -65 TO 150 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE CYCLES</b>	<b>No. of FAILURES</b>
QFN/DFN	4991	0325	1321	1268	0
SSOP/TSSOP	2241	0734	1322	500	0
SOIC/SOT/MSOP	10015	9924	1317	1834	0
SOT	3444	0502	1317	823	0
Totals	20,691	-	-	4,425	0

<b>HIGH TEMPERATURE BAKE AT 150 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE HRS</b>	<b>No. of FAILURES</b>
QFN/DFN	445	0743	1252	395	0
SSOP/TSSOP	50	1018	1018	25	0
Totals	495	-	-	420	0

(1) Assumes Activation Energy = 0.7 Electron Volts  
 (2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =2.9 FITS  
 (3) Mean Time Between Failure in Years = 39413.18  
 Note 1: 1 FIT = 1 Failure in One Billion Hours.  
 Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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<b>HIGH TEMPERATURE BAKE AT 175 DEG C</b>					
<b>PACKAGE TYPE</b>	<b>SAMPLE SIZE</b>	<b>OLDEST DATE CODE</b>	<b>NEWEST DATE CODE</b>	<b>K DEVICE HRS</b>	<b>No. of FAILURES</b>
SSOP/TSSOP	50	1018	1018	25	0
SOIC/SOT/MSOP	400	0838	1301	300	0
SOT	298	0831	0909	298	0
Totals	748	-	-	623	0